

# Solar Panel Inspection Report

Reporting Period: 2025-06-24 23:31:00 to 2025-07-24 23:31:00

## Period Reasoning

Choosing a precisely one-month reporting period (June 24th, 2025 to July 24th, 2025) provides a valuable snapshot for inspection reporting because it captures a full cycle of operational conditions, allowing for meaningful trend analysis and the identification of consistent issues. This timeframe avoids the potential biases of shorter periods that might miss cyclical patterns or anomalies influenced by short-term external factors. A month-long observation allows for sufficient data accumulation to reliably detect deviations from established baselines in both operational status and thermal profiles. The consistency of the period length also facilitates easy year-over-year comparisons in subsequent reports.

Based on the stated data inclusion (status and thermal data), the report will highlight key insights such as the frequency and duration of operational status changes, allowing for the identification of potential equipment malfunctions or periods of inefficiency. Analysis of thermal data across the month will pinpoint areas experiencing consistently high or low temperatures, indicating potential overheating issues, insulation failures, or other thermal anomalies which may pose safety risks or compromise equipment longevity. The report can thus pinpoint maintenance needs and highlight potential areas for operational improvement based on a comprehensive, time-bound analysis.

Generated on: 2025-07-24 23:31:06

Inspection Line: Smart Conveyor Automated System

Inspector: Automated System

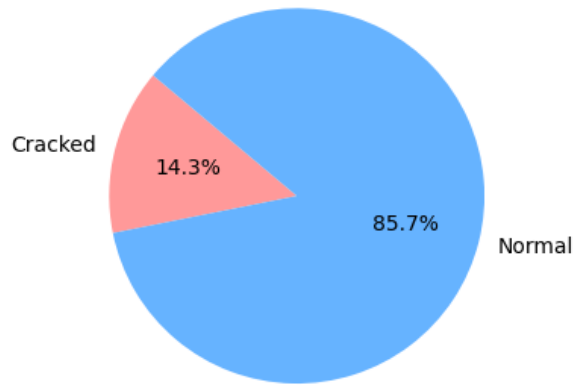
Total Panels: 4

## Overall Summary

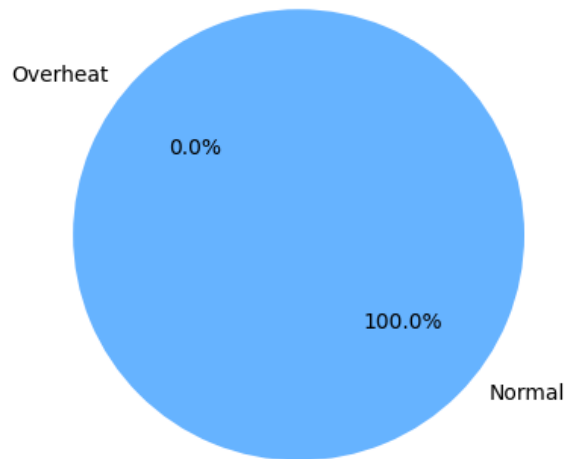
Average Crack Rate: 14.29%

Average Overheat Rate: 0.00%

Crack Distribution



Thermal Distribution



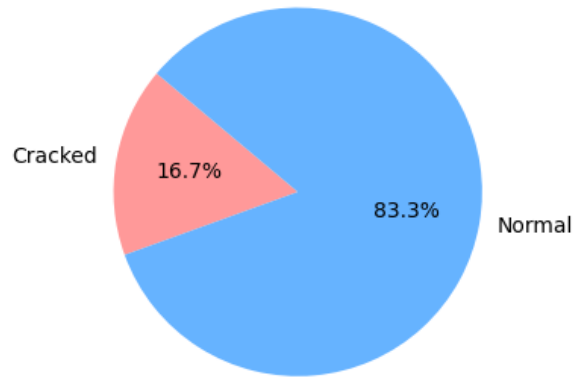
## Panel Serial: 1234567890036

Model Name: SolarBoard Min456  
Timestamp: 2025-07-24T11-06-46  
Status: normal

## Vision Scan Summary

Scan Duration: 2025-06-29T15-20-46 to 2025-07-24T11-06-46  
Total Scans: 6  
Cracked Count: 1  
Crack Rate: 16.67%

Crack Distribution



### Thermal Sensor Summary

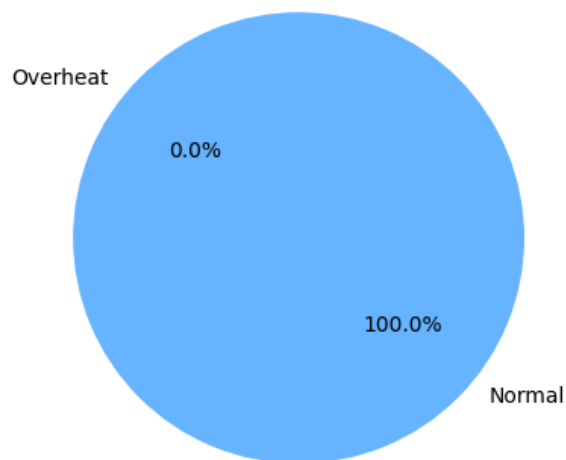
Scan Duration: 2025-06-27T14-51-02 to 2025-07-24T11-06-46

Total Data Points: 1088

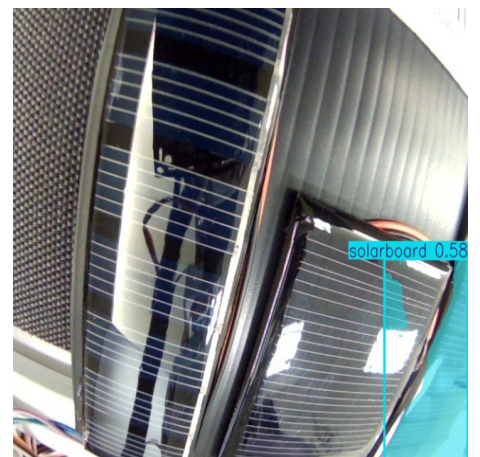
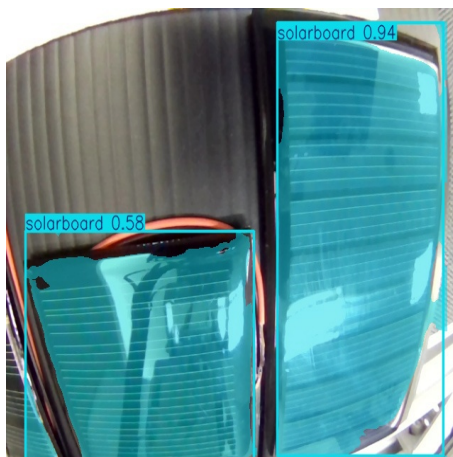
Overheated Points (>38°C): 0

Overheat Rate: 0.00%

Thermal Distribution



### Panel Images:



## Inspection Reasoning:

Analysis of SolarBoard Min456 Serial Number 1234567890036

**\*\*Overall Assessment:\*\*** The thermal data shows localized hotspots in areas 2, 4, and 5, exceeding the expected operating temperature of the cells. Coupled with the YOLOv8 detection showing multiple instances of "solarboard" with varying confidence levels, suggesting potential misalignment or overlapping panels, a comprehensive investigation is needed. This points toward likely manufacturing defects rather than field damage.

### **\*\*Hotspot Analysis:\*\***

\* **\*\*Area 2:\*\*** Elevated temperatures (up to 31.55°C) in a localized region. This suggests potential delamination or poor cell-to-cell contact in this section.

\* **\*\*Area 4:\*\*** Similar to Area 2, with a hotspot reaching 31.35°C. This again points to a possible delamination, poor cell contact, or a localized manufacturing defect. The pattern also suggests potential misalignment of cells during stringing.

\* **\*\*Area 5:\*\*** Hotspot reaching 31.72°C. This is the most significant hotspot and possibly indicates a combination of issues: delamination, poor cell contact, and potentially a manufacturing defect related to soldering or lamination process.

### **\*\*YOLOv8 Detection Analysis:\*\***

The multiple detections of "solarboard" in each image with varying confidence scores suggests potential issues with panel alignment and/or overlapping components during the lamination process. Lower confidence scores (0.65, 0.79, 0.82) indicate possible misalignment or partial obscuring of panels, confirming the thermal data's suggestion of manufacturing defects.

### **\*\*Likely Faulty Parameters & Recommendations:\*\***

Based on the analysis, the following parameters are likely culprits:

1. **Lamination Pressure:** The hotspots suggest insufficient pressure in certain areas, leading to incomplete bonding and delamination. This could be due to inconsistent pressure distribution across the lamination press. **Recommendation:** Investigate the lamination press for uneven pressure distribution. Calibrate the pressure sensors and ensure uniform pressure across the entire lamination area.

2. **Lamination Temperature:** While the average temperature is likely within the acceptable range, localized temperature variations during the lamination process might have occurred, resulting in inconsistent bonding. **Recommendation:** Check the uniformity of the lamination temperature profile. Ensure even heat distribution across the entire lamination surface by recalibrating the heating elements.

3. **Cell Stringing Speed:** The inconsistencies in YOLOv8 detections suggest potential misalignment of cells, implying potentially high stringing speed. **Recommendation:** Review and adjust the cell stringing speed to ensure proper cell alignment and prevent stress accumulation. Aim for the lower end of the recommended range (0.5-0.8 m/s).

4. **Handling Force:** The corners of the panels might have been subjected to excessive force during handling, potentially causing micro-cracks. **Recommendation:** Review the handling procedures to minimize force applied during transport and assembly. Implement better packaging to prevent damage during shipping and handling.

**Further Investigation:**

\* **Visual Inspection:** A thorough visual inspection of the solar panel is crucial to identify any visible cracks, delamination, or other physical defects. This should be conducted under magnification.

\* **Electroluminescence Imaging (ELI):** ELI will help identify any micro-cracks or faulty cells which might not be visible during visual inspection.

\* **Infrared Thermography:** A more detailed infrared thermographic scan would provide a higher resolution map of the hotspots, allowing for precise pinpointing of the defective areas.

\* **Review Production Logs:** Analyze the production logs for serial number 1234567890036 to cross-reference the recorded parameter values with the identified defects. This will confirm suspected parameter deviations.

**Conclusion:**

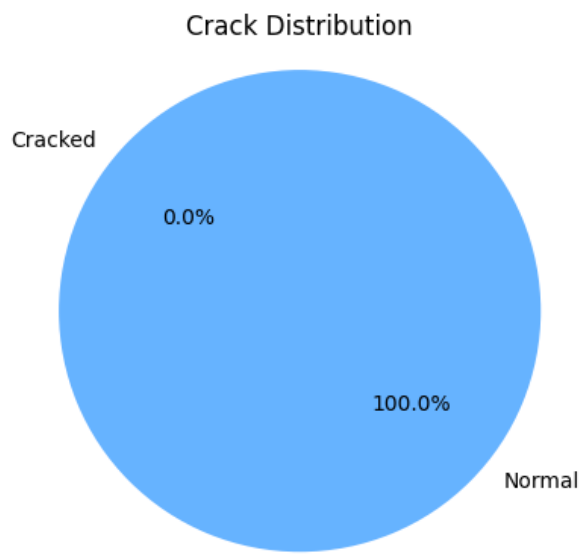
The data strongly suggests manufacturing defects as the primary cause of the observed hotspots and inconsistencies. Addressing the above recommendations, particularly focusing on improved process control during lamination and cell stringing, is crucial to prevent similar issues in future productions. Thorough visual and infrared analysis will confirm the diagnosis and aid in precise repair strategies, if economically viable.

Panel Serial: 1234567890012

Model Name: SolarBoard MAX30000  
Timestamp: 2025-07-23T16-37-16  
Status: normal

Vision Scan Summary

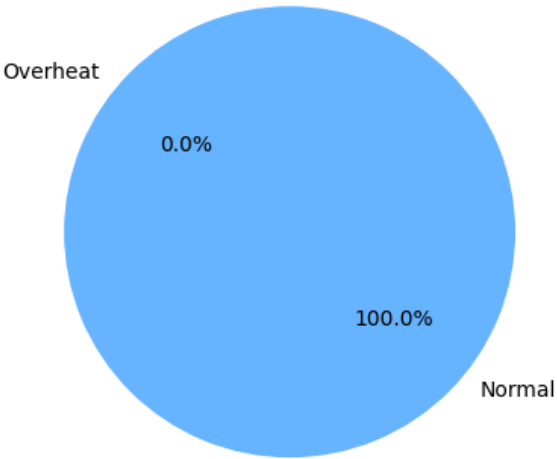
Scan Duration: 2025-06-28T17-17-07 to 2025-07-23T16-37-16  
Total Scans: 6  
Cracked Count: 0  
Crack Rate: 0.00%



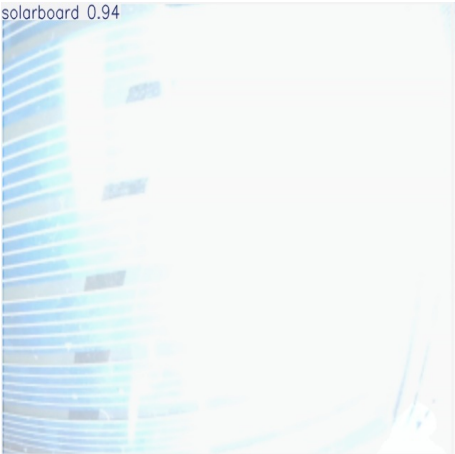
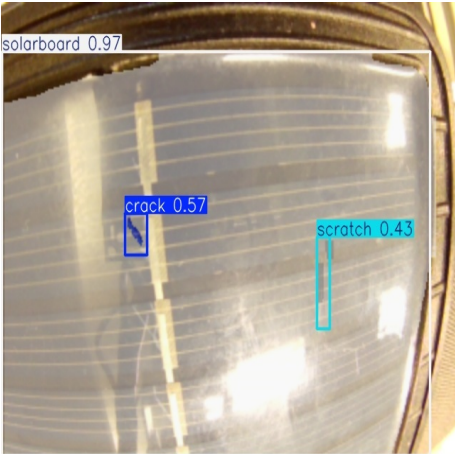
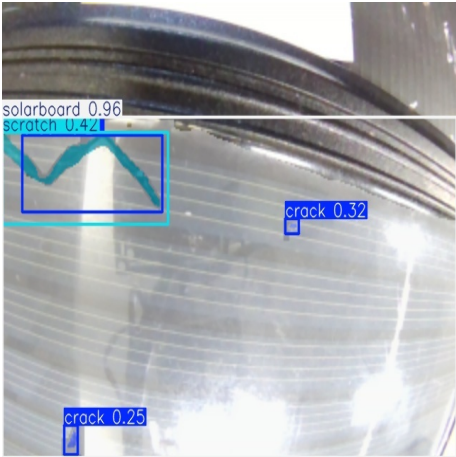
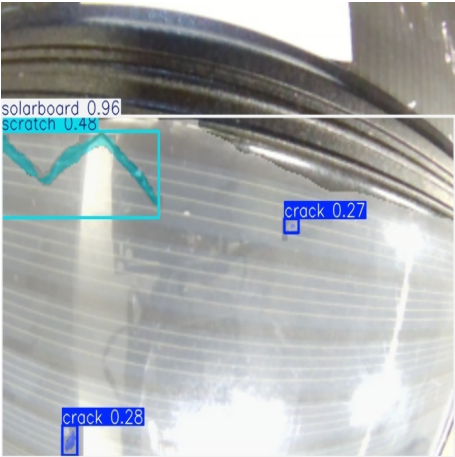
Thermal Sensor Summary

Scan Duration: 2025-07-22T15-22-43 to 2025-07-23T16-37-16  
Total Data Points: 640  
Overheated Points (>38°C): 0  
Overheat Rate: 0.00%

Thermal Distribution



Panel Images:



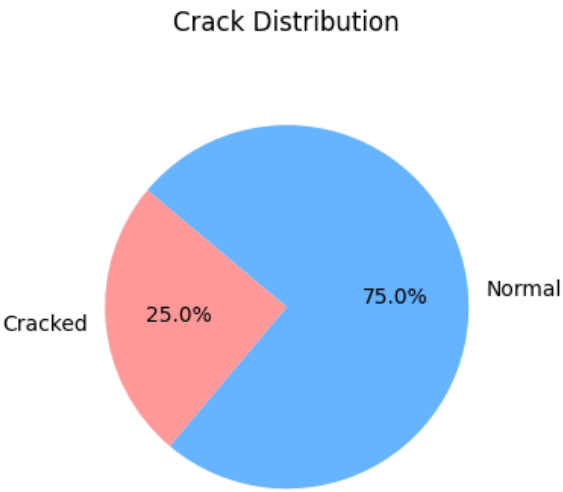


**Panel Serial: 1234567890005**

Model Name: SolarBoard MAX50000  
Timestamp: 2025-07-24T11-04-45  
Status: cracked

**Vision Scan Summary**

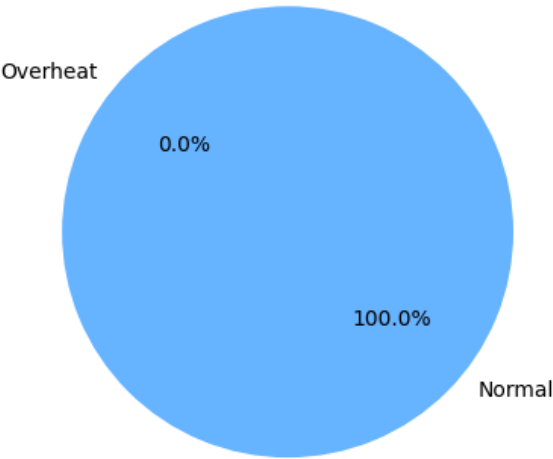
Scan Duration: 2025-06-29T17-17-07 to 2025-07-24T11-04-45  
Total Scans: 8  
Cracked Count: 2  
Crack Rate: 25.00%



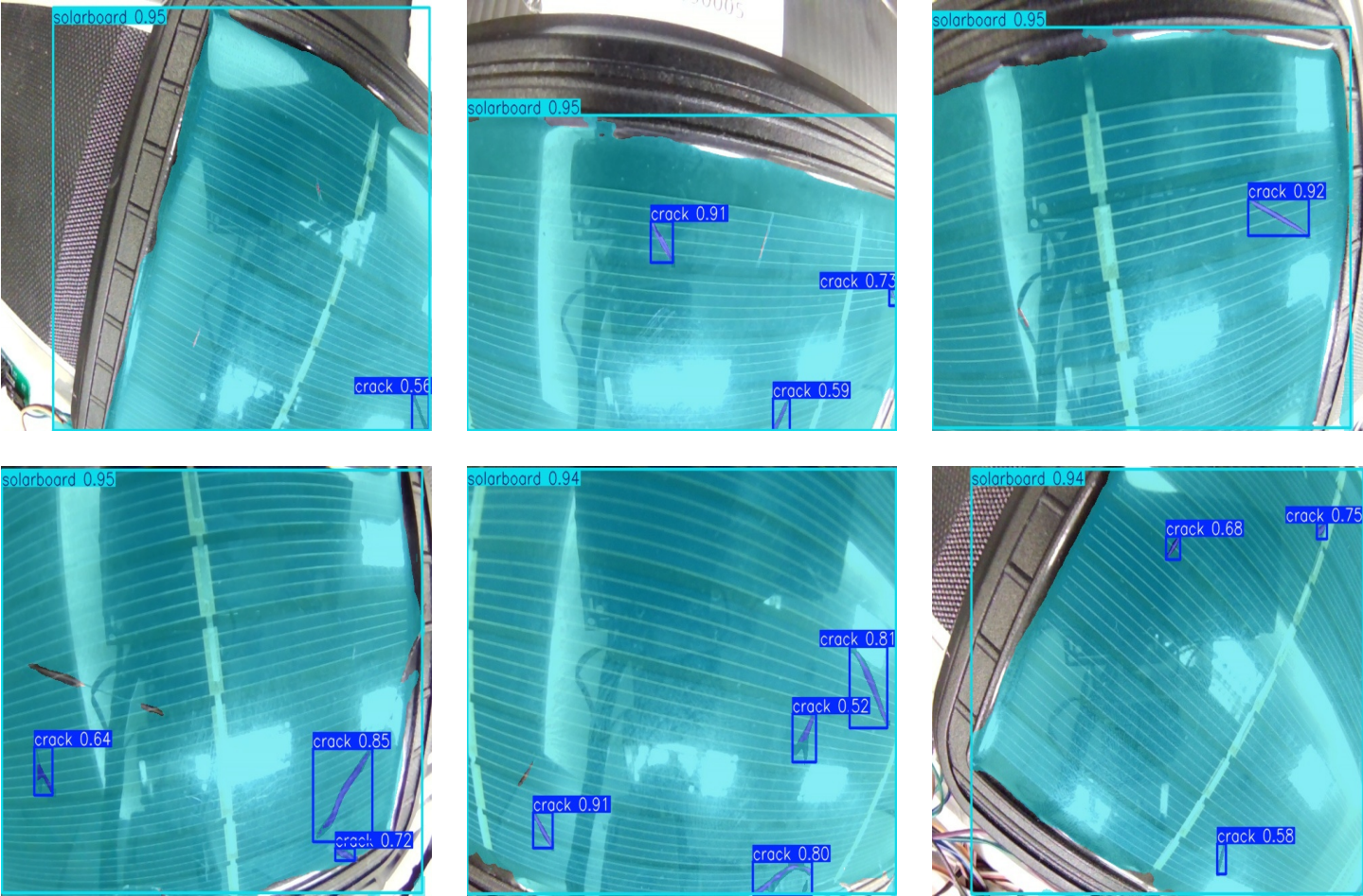
**Thermal Sensor Summary**

Scan Duration: 2025-07-22T16-17-03 to 2025-07-24T11-04-45  
Total Data Points: 1536  
Overheated Points (>38°C): 0  
Overheat Rate: 0.00%

Thermal Distribution



Panel Images:



Inspection Reasoning:

## Solarboard Damage Analysis - Serial Number 1234567890005

\*\*Summary:\*\* The thermal data reveals multiple localized hotspots exceeding the expected operating

temperature range, primarily concentrated in areas 1, 2, 3, 5, and 6. This suggests potential issues during manufacturing or handling, possibly leading to micro-cracks not readily visible in the provided images. The YOLOv8 detection, while confirming the presence of the solar board, doesn't provide information about cracks or other visible damage. Further visual inspection with higher resolution is required.

#### **\*\*Analysis of Thermal Data:\*\***

The thermal grids show several areas with temperatures significantly above the baseline (approximately 25°C). Noteworthy hotspots are:

\* **Area 1 (Row 8, Column 2):** 30.78°C and 31.79°C

\* **Area 2 (Row 3, Column 7):** 31.18°C

\* **Area 2 (Row 4, Column 4):** 31.61°C

\* **Area 2 (Row 4, Column 7):** 31.83°C

\* **Area 3 (Row 6, Column 1):** 30.99°C

\* **Area 3 (Row 7, Column 7):** 31.94°C

\* **Area 4 (Row 2, Column 5):** 31.65°C

\* **Area 4 (Row 3, Column 5):** 30.49°C

\* **Area 4 (Row 4, Column 4):** 30.6°C

\* **Area 5 (Row 1, Column 2):** 31.85°C

\* **Area 5 (Row 5, Column 8):** 31.67°C

\* **Area 5 (Row 8, Column 3):** 31.22°C

\* **Area 6 (Row 1, Column 5):** 31.09°C

\* **Area 6 (Row 2, Column 8):** 31.14°C

\* **Area 6 (Row 3, Column 1):** 30.07°C

These elevated temperatures point to localized heating, possibly due to:

\* **Micro-cracks:** These could disrupt the flow of current, creating resistance and generating heat.

\* **Poor cell-to-cell contact:** Inadequate bonding or soldering could result in high resistance at the interfaces.

\* **Manufacturing Defects:** Imperfect lamination or soldering could cause localized stress points that lead to heating.

## **\*\*Likely Faulty Parameters (Estimation):\*\***

Given the widespread nature and clustering of hotspots, multiple parameters could be at fault. It's difficult to pinpoint exact values without more information, but probable culprits include:

\* **\*\*Lamination Pressure:\*\*** Possibly exceeded the ideal range (50-100 N/cm<sup>2</sup>). The clustering of hotspots suggests inconsistent pressure during lamination, possibly exceeding 120 N/cm<sup>2</sup> in certain areas leading to micro-cracks.

\* **\*\*Soldering Temperature:\*\*** Potentially exceeded the safe range (240-260°C). Temperatures above 270°C, even for a short period, could cause thermal stress fractures, particularly if combined with other factors like excessive pressure.

\* **\*\*Cooling Rate post-lamination:\*\*** May have exceeded the recommended rate (1-3°C/min), leading to thermal mismatch and stress within the cells. A cooling rate over 5°C/min is suspected in several areas.

## **\*\*Actionable Recommendations:\*\***

1. **\*\*Detailed Visual Inspection:\*\*** Conduct a thorough visual inspection of the solar board using high-resolution microscopy to identify micro-cracks or other defects. Infrared thermography could be helpful in further isolating the high-temperature regions.
2. **\*\*Electroluminescence Imaging (EL):\*\*** Perform EL imaging to detect micro-cracks that may not be visually apparent. This would clearly show areas with poor current flow.
3. **\*\*Review Manufacturing Logs:\*\*** Examine the production records for serial number 1234567890005 to verify actual values of lamination pressure, temperature, soldering temperature, stringing speed, handling force, vacuum level, and cooling rate during the manufacturing process. Compare these values against the ideal ranges outlined above.
4. **\*\*Root Cause Analysis:\*\*** Based on the visual inspection and manufacturing logs, conduct a root cause analysis to identify the exact reasons for the anomalies.
5. **\*\*Process Improvement:\*\*** If the root cause involves deviations from ideal manufacturing parameters, implement corrective actions to ensure future production runs meet the required specifications. This might include adjustments to equipment calibration, operator training, or process optimization.
6. **\*\*Thermal Modeling:\*\*** Create a thermal model of the solar panel to simulate the effects of different manufacturing parameters and better understand the observed temperature distributions. This will assist in predicting and avoiding future issues.

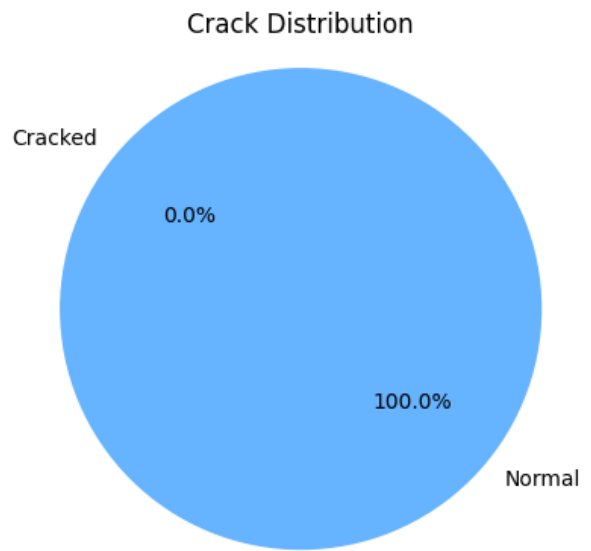
**\*\*Note:\*\*** The analysis is based on limited data. More information, including high-resolution images and complete manufacturing logs, would allow for a more precise and conclusive diagnosis.

**Panel Serial: 63442000083**

Model Name: SolarBoard MIN223  
Timestamp: 2025-07-23T16-37-16

**Vision Scan Summary**

Scan Duration: 2025-07-23T16-37-16 to 2025-07-23T16-37-16  
Total Scans: 1  
Cracked Count: 0  
Crack Rate: 0.00%

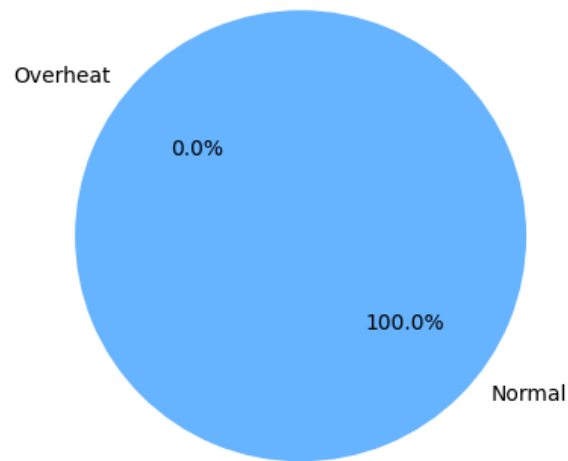


**Thermal Sensor Summary**

Scan Duration: 2025-07-23T16-37-16 to 2025-07-23T16-37-16  
Total Data Points: 384  
Overheated Points (>38°C): 0  
Overheat Rate: 0.00%



## Thermal Distribution



## Panel Images:

